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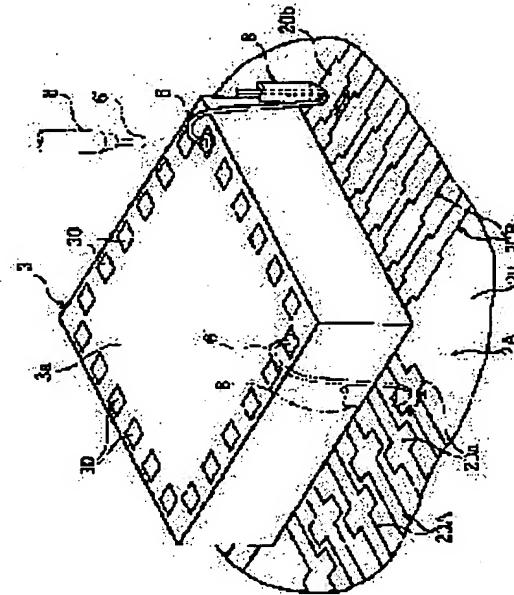
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(54) MANUFACTURE OF SEMICONDUCTOR DEVICE

(57)Abstract:

PROBLEM TO BE SOLVED: To enhance connecting strength between a wire and the wire bonding pad of a substrate in the manufacturing method of a semiconductor device, including the wire-bonding process for imparting ultrasonic vibration.

SOLUTION: A semiconductor chip 3 having a plurality of terminal parts 30, etc., are mounted on a substrate 2A, where the wiring pattern comprising a plurality of lead terminals parts 20, etc., (20B, etc.), having wire-bonding pads 20a (20b) is formed on one-surface side. The part between each terminal part 30 of the semiconductor chip 3 and each wire-bonding pad 20a (20b) are connected with a wire 6'. In this manufacturing method for semiconductor device which includes this process, the respective wire-bonding pad 20a (20b) is formed so that the dimension in one direction is longer than the dimension in the direction perpendicular to this one direction. When the wire 6' is bonded to the respective wire-bonding pads 20a (20b), the direction of the vibration is made to coincide with the one direction, and ultrasonic waves are imparted.



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